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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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HD74HC589

8-bit Serial or Parallel-input/Serial-output Shift Register (with 3-state outputs)



ADE-205-511 (Z)
1st. Edition
Sep. 2000

Description

The HD74HC589 is similar in function to the HD74HC597, which is not a 3-state device.

This device consists of an 8-bit storage latch which feeds parallel data to an 8-bit shift register. Data can also be loaded serially (see Function Table). The shift register output, O_H , is a three-state output, allowing this device to be used in bus-oriented systems.

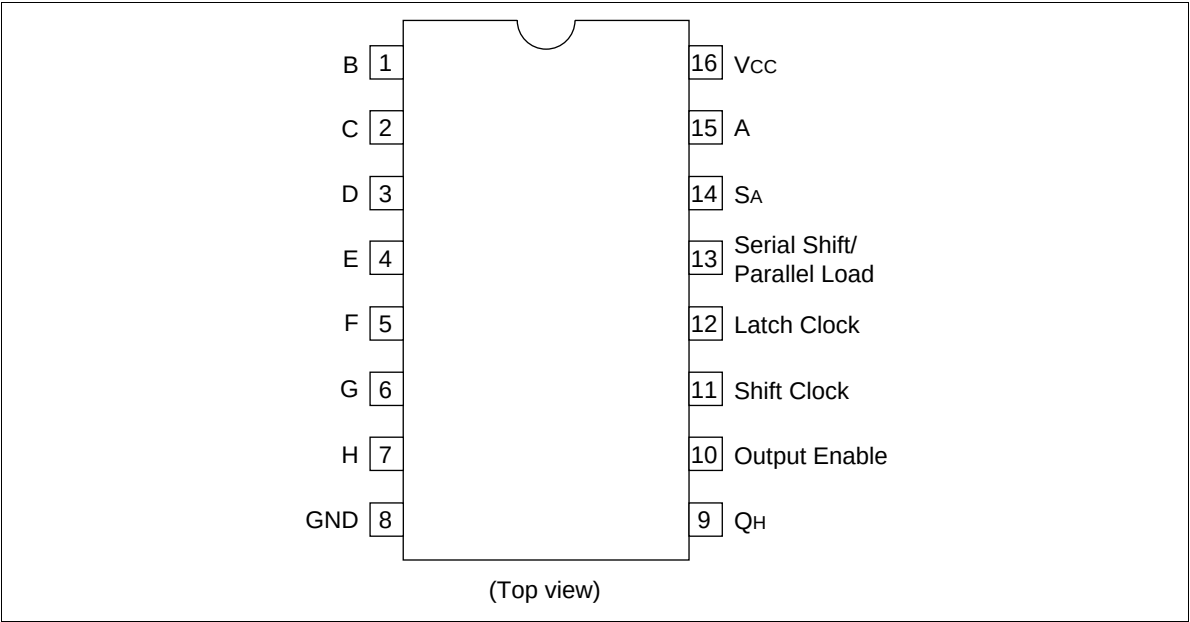
Features

- High Speed Operation: t_{pd} (Shift Clock to Q_H) = 15 ns typ (C_L = 50 pF)
- High Output Current: Fanout of 15 LSTTL Loads
- Wide Operating Voltage: V_{CC} = 2 to 6 V
- Low Input Current: 1 μ A max
- Low Quiescent Supply Current: I_{CC} (static) = 4 μ A max (T_a = 25°C)

Function Table

Latch Clock LCK	Shift Clock SCK	Serial Shift/ Parallel Load	Output Enable $\overline{OE}$	Function
	X	X	X	Data are loaded into input latches
	X	L	L	Data are loaded from input into shift registers
X	X	L	L	Data are transferred from input latches to shift registers
L, H, 	L, H, 	X	H	Outputs are disabled
X		H	L	Serial shift $Q_n = Q_{n-1}$, $Q_0 = SER$

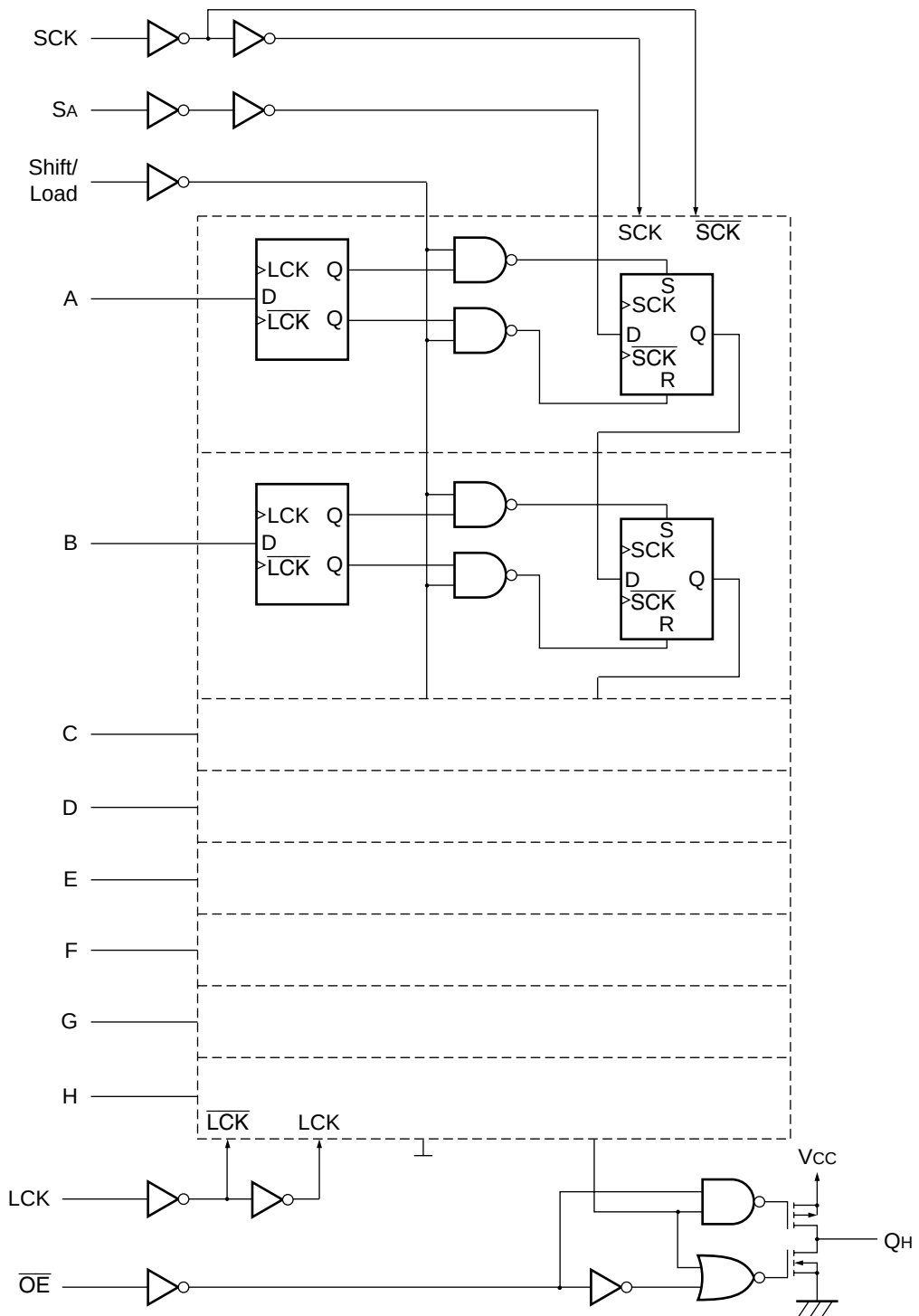
Pin Arrangement



Absolute Maximum Ratings

Item	Symbol	Rating	Unit
Supply voltage range	V_{CC}	-0.5 to +7.0	V
Input voltage	V_{IN}	-0.5 to $V_{CC} + 0.5$	V
Output voltage	V_{OUT}	-0.5 to $V_{CC} + 0.5$	V
Output current	I_{OUT}	±35	mA
DC current drain per V_{CC} , GND	I_{CC} , I_{GND}	±75	mA
DC input diode current	I_{IK}	±20	mA
DC output diode current	I_{OK}	±20	mA
Power Dissipation per package	P_T	500	mW
Storage temperature	T_{stg}	-65 to +150	°C

Logic Diagram



DC Characteristics

Item	Symbol	V _{CC} (V)	Ta = 25°C			Ta = -40 to +85°C		Unit	Test Conditions	
			Min	Typ	Max	Min	Max			
Input voltage	V _{IH}	2.0	1.5	—	—	1.5	—	V		
		4.5	3.15	—	—	3.15	—			
		6.0	4.2	—	—	4.2	—			
	V _{IL}	2.0	—	—	0.5	—	0.5	V		
		4.5	—	—	1.35	—	1.35			
		6.0	—	—	1.8	—	1.8			
Output voltage	V _{OH}	2.0	1.9	2.0	—	1.9	—	V	Vin = V _{IH} or V _{IL} I _{OH} = -20 μA	
		4.5	4.4	4.5	—	4.4	—			
		6.0	5.9	6.0	—	5.9	—			
		4.5	4.18	—	—	4.13	—			I _{OH} = -6 mA
		6.0	5.68	—	—	5.63	—			I _{OH} = -7.8 mA
	V _{OL}	2.0	—	0.0	0.1	—	0.1	V	Vin = V _{IH} or V _{IL} I _{OL} = 20 μA	
		4.5	—	0.0	0.1	—	0.1			
		6.0	—	0.0	0.1	—	0.1			
		4.5	—	—	0.26	—	0.33			I _{OL} = 6 mA
		6.0	—	—	0.26	—	0.33			I _{OL} = 7.8 mA
Off-state output current	I _{OZ}	6.0	—	—	±0.5	—	±5.0	μA	Vin = V _{IH} or V _{IL} , Vout = V _{CC} or GND	
Input current	I _{in}	6.0	—	—	±0.1	—	±1.0	μA	Vin = V _{CC} or GND	
Quiescent supply current	I _{CC}	6.0	—	—	4.0	—	40	μA	Vin = V _{CC} or GND, Iout = 0 μA	

AC Characteristics ($C_L = 50 \text{ pF}$, Input $t_r = t_f = 6 \text{ ns}$)

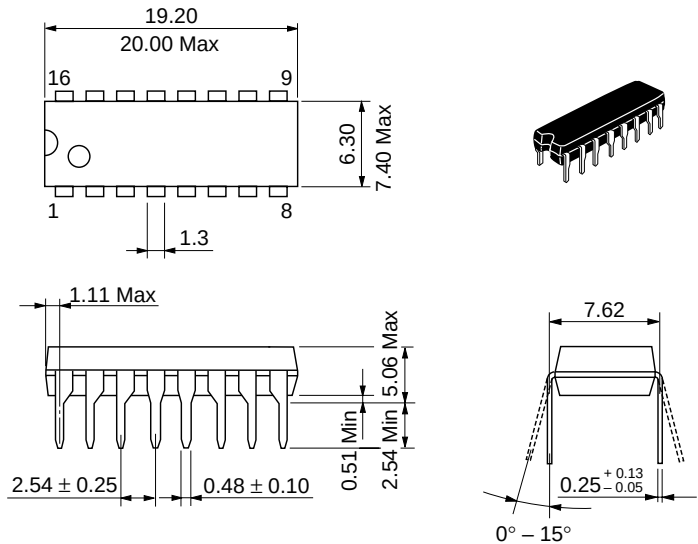
Item	Symbol	V _{CC} (V)	Ta = 25°C						Unit	Test Conditions
			Min			Typ				
			Max			Min				
				Ta = −40 to +85°C						
Maximum clock frequency	f _{max}	2.0	—	—	5	—	4	MHz		
		4.5	—	—	27	—	21			
		6.0	—	—	32	—	25			
Propagation delay time	t _{PLH}	2.0	—	—	200	—	250	ns	Latch clock to Q _H	
		4.5	—	20	40	—	50			
		6.0	—	—	34	—	43			
	t _{PHL}	2.0	—	—	175	—	220	ns	Shift clock to Q _H	
		4.5	—	15	35	—	44			
		6.0	—	—	30	—	37			
	t _{PLH}	2.0	—	—	175	—	220	ns	Serial shift/prallel load to Q _H	
		4.5	—	16	35	—	44			
		6.0	—	—	30	—	37			
	t _{PHL}	2.0	—	—	150	—	190	ns		
		4.5	—	9	30	—	38			
		6.0	—	—	26	—	33			
Output enable time	t _{ZL}	2.0	—	—	150	—	190	ns		
		4.5	—	9	30	—	38			
		6.0	—	—	26	—	33			
Output disable time	t _{LZ}	2.0	—	—	150	—	190	ns		
		4.5	—	14	30	—	38			
		6.0	—	—	26	—	33			
Pulse width	t _w	2.0	80	—	—	100	—	ns		
		4.5	16	8	—	20	—			
		6.0	14	—	—	17	—			
Setup time	t _{su}	2.0	100	—	—	125	—	ns	Data to latch clock	
		4.5	20	1	—	25	—			
		6.0	17	—	—	21	—			
	t _{su}	2.0	100	—	—	125	—	ns	S _A to shift clock	
		4.5	20	—	—	25	—			
		6.0	17	—	—	21	—			
	t _{su}	2.0	100	—	—	125	—	ns	Serial shift/parallel load to shift clock	
		4.5	20	—	—	25	—			
		6.0	17	—	—	21	—			

AC Characteristics (C_L = 50 pF, Input t_r = t_f = 6 ns) (cont)

Item	Symbol	V _{CC} (V)	Ta = 25°C			Ta = -40 to +85°C		Unit	Test Conditions
			Min	Typ	Max	Min	Max		
Hold time	t _h	2.0	5	—	—	5	—	ns	Latch clock to data
		4.5	5	0	—	5	—		
		6.0	5	—	—	5	—		
	t _h	2.0	5	—	—	5	—	ns	Shift clock to S _A
		4.5	5	—	—	5	—		
		6.0	5	—	—	5	—		
	t _h	2.0	5	—	—	5	—	ns	Shift clock to serial shift/ parallel load
		4.5	5	—	—	5	—		
		6.0	5	—	—	5	—		
Output rise/fall time	t _{TLH}	2.0	—	—	75	—	95	ns	
	t _{THL}	4.5	—	5	15	—	19		
		6.0	—	—	13	—	16		
Input capacitance	C _{in}	—	—	5	10	—	10	pF	

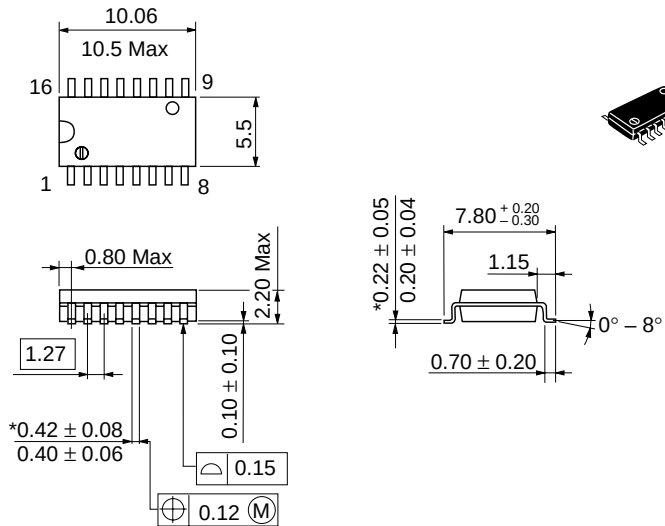
Package Dimensions

Unit: mm



Hitachi Code	DP-16
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	1.07 g

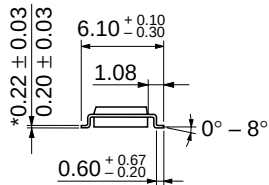
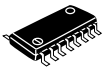
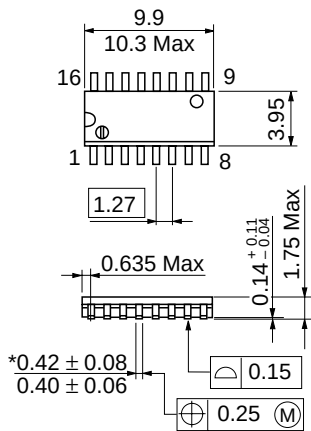
Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-16DA
JEDEC	—
EIAJ	Conforms
Mass (reference value)	0.24 g

Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-16DN
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	0.15 g

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